Trade Name: LFM-48W GT

1. Company Address

Almit GmbH
Unterer Hammer 3
Deutschland
(D) 64720 Michelstadt -
bei Frankfurt

Tel.: +49 6061 96925-0
Fax: +49 6061 96925-18

2. Validity

This specification is specified for:
Solder Paste Lead Free LFM-48W GT
Delivered by Almit GmbH to:

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3. Diameter & Allowence

Weight	20g	40g	100g	250g	80g
Allowance	-0, +5g				

4. Deliverable Reel Size

Metal Name	Solidus °C	Liquidus °C	Specific Gravity
LFM-48	217	220	7.4

5. Physical Properties

Test	Characteristics	Test Methods
Metal Content	88.0 ± 1.0	IPC-TM-650 2.2.20
Silver Chromate	pass	IPC-TM-650 2.3.33
Copper Mirror Test	pass	IPC-TM-650 2.3.32
SIR (85°C, 85%, 168hr) (Ω)	≥ 1 x 10^8	IPC-TM-650:2.6.3.3
Corrosion Test	pass	IPC-TM-650 2.6.15
Flux materials composition	RO	J-STD-004 1.2
Quantitative Halide	L1 < 0.5%	IPC-TM-650 2.3.35
Fluorides By Spot Test	pass	IPC-TM-650 2.6.35.1

6. Characteristics

Composition	Components							
	Sn	Ag	Cu	Pb	Sb	Bi	Au	In
Standard	Rest	3.0	0.5	<0.05	≤0.10	≤0.05	≤0.05	≤0.10
Composition	Components							
	Al	As	Cd	Fe	Ni	Zn		
Standard	≤0.001	≤0.03	≤0.002	≤0.02	≤0.01	≤0.001		

7. Solder Powder Size & Distribution

Type	larger than	less than 1%	at least 80%	at most 10%
Type 4 V16L	40 Microns	38 Microns	20 - 38 Microns	20 Microns

8. Lot Size

A single lot is consisted of, and may vary between 10 - 100kg, depends upon the production plan.

9. Quality and Inspection

Inspection items are applied to each lot as follows:

Test No.	Inspection Item	Contents	Standard	
1	Appearance	Color	Comparison with Limit Specimen	
2	Weight	Net Weight	-0 ; +5	(g)
3	Solder Powder Size	20-38 µm	94 ≤	(wt%)
4	Metal Composition	Sn	Rest	(wt%)
		Ag	3.0 ± 0.2	(wt%)
		Cu	0.5 ± 0.1	(wt%)
5	Characteristics	Flux Content	13.0 ± 0.5	(wt%)
		Solder Balling Test	Comparison with Limit Specimen	
		Viscosity (Spiral type, 10rpm, 25°C) (IPC-650-2.4.34.3)	190000 ± 30000 190 ± 30	(cps) (Pa.s)
		Solderability on Cu-Plate	Comparison with Limit Specimen	
		Dryness	Chalk powder should be easily removed from each test specimen.	

*Straight lines of solder paste are printed on a JIS-2 type substrate then reflowed. The reflowed solder is examined with a stereo microscope at 30X magnification. No more than 2 solder balls larger than one fifth the size of the pattern gap is allowed per gap.

10. Packing

Individual Package		Outer Package	
Unit	Packing	Unit	Packing
20g	5cc Cartridge		Cardboard box
40g	10cc Cartridge		
80g	30cc Cartridge		
100g	30cc Cartridge		
250g	100cc Cartridge		

11. Identification

	Polyethylene bottle	Cardboard
Name	LFM-48W GT	same as the left
Lot Nr.	(Ex) 120119-9	dto.
Solder Powder Size	V16L	dto.
Date of Mfg.	(Ex.) 19.01.2012	dto
Net-Weight	(Ex.) 500g	dto.
Maker	Nihon Almit Co. Ltd.	dto.

12. Maker Address

Nihon Almit Co. Ltd.
Almit Bldg., 2-14-2 Yayoicho, Nakano-ku,
Tokyo, Japan

13. In case of changing this specification it should be accepted by

Signature_____ Date_____

14. This product is manufactured, using all guaranteed materials according to the legal law regulations

15. Shelf Life

1. Refrigerating is recommended at a temperature of 2-8°C to guarantee shelf life of 4 months
2. Paste can be stored at room temperature for 1 week up to 25°C prior to use (only applicable for jars)